

Abstract

The present invention creates an optical sensor assemblage, in particular a thermopile sensor assemblage, comprising a sensor chip assemblage (10; 10') having an optically transparent irradiation region (OB; OB'), a mounting region (RB; RB') surrounding the latter, and a wire-bond region (BB); an optically isolating mounting frame (MLF; MLF') having a chip receiving region (DP; DP') and a plurality of connector elements (AB-AB'''); and an optically isolating packaging device (MV-MV'''); the sensor chip assemblage (10; 10') being joined in the mounting region (RB; RB') to the chip receiving region (LB; LB'), and in the wire-bond region (BB) to one or more of the connector elements (AB-AB'''); the chip receiving region (DP, DP') having a window (F; F') disposed in such a way that at least a portion of the optical irradiation region (OB; OB') is not covered by the chip receiving region (DP; DP'); and the packaging device (MV-MV''') surrounding the sensor chip assemblage (10; 10') and the mounting frame (MLF; MLF') in such a way that optical radiation can enter the sensor chip assemblage (10; 10') substantially only through the window (F; F').

(Figure 1c)